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DIALOG(R)File 352:Derwent WPI

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Unsaturated polyester resin composition - cured using organic peroxides made up of two parts having both ten hour half-lives at different temperatures
Patent Assignee: SEKISUI CHEM IND CO LTD (SEKI)
Number of Countries: 001 Number of Patents: 001
Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week	
JP 10036653	A	19980210	JP 96187576	A	19960717	199816	B

Priority Applications (No Type Date): JP 96187576 A 19960717
Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 10036653	A		7	C08L-067/06	

Abstract (Basic): JP 10036653 A
A 0.5-10 pts.wt. organic peroxide is added to the 100 pts.wt.-resin portion of an unsatd. polyester resin. The organic peroxide contains: (a) a first organic peroxide having a 10-hour half life temp. of 50 deg. C or more and less than 85 deg. C; and (b) a sec. organic peroxide having a 10-hour half life temp. of 85 deg. C or more and less than 110 deg. C with a wt. ratio of 1:9-9:1. Also claimed is that thermal compression moulding is applied to the unsatd. polyester resin compsn. Where, the temp. of a die site for forming the thick-wall section of a moulded part is higher than the temp. of the die site for forming the thin-wall section of the moulded part by 5-100 deg. C.
USE - The unsatd. polyester resin compsn. and the thermal compression moulding yield the moulded part.
ADVANTAGE - The method prolongs the gelatinisation duration to evolve less pregel, and reduces the duration before completing hardening. The resulting moulded part has no poor surface, including the pregel. The method yields the moulded part having the thick-wall portion in a short compression period of time.
Dwg. 0/3
Derwent Class: A23
International Patent Class (Main): C08L-067/06
International Patent Class (Additional): B29C-043/02; B29C-043/52